

<b>PCN Number:</b>	20160317000		<b>PCN Date:</b>	3/21/2016	
<b>Title:</b>	Qualify TI Clark as an additional Bump, Assembly, & Test site for the TPS22913CZV.				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services		
<b>Proposed 1<sup>st</sup> Ship Date:</b>	6/21/2016	<b>Estimated Sample Availability:</b>	Provided upon Request		
<b>Change Type:</b>					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input checked="" type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
<b>PCN Details</b>					
<b>Description of Change:</b>					
<p>Texas Instruments is pleased to announce the qualification of TI Clark as an alternate Bump, Assembly, and Test site for the devices shown below. The material set will be the same between the 2 sites.</p> <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>					
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Anticipated impact on Material Declaration</b>					
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI ECO website</a> .		
<b>Changes to product identification resulting from this PCN:</b>					
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (21L)</b>	<b>Assembly City</b>		
JCAP	JCP	CHN	Jiangsu		
<b>TI Clark</b>	<b>QAB</b>	<b>PHL</b>	<b>Angeles City, Pampanga</b>		

Sample product shipping label (not actual product label)





MADE IN: Malaysia  
2DC: 2Q:

MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:  
ITEM: 39  
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO:USA  
(22L) ASO: MLA (23L) ACO: MYS

**Topside Device marking:**

Assembly site code for JCP= P

**Assembly site code for QAB = I**

**Product Affected**

TPS22913CYZVR	TPS22913CYZVT
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TI Information  
Selective Disclosure

**Qualification Report**

**TPS22913CYZVR (JCAP to CLARK)**

Approve Date 26-Jan-2016

**Product Attributes**

Attributes	QBS Product Reference: TPD12S015YFF	QBS Package Reference: SN74LVC1G04YZVR	QBS Package Reference: TXS0104EYZTR
Assembly Site	TI-CLARK	CLARK	CLARK
Package Family	-	WCSP	WCSP
Flammability Rating	-	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	FREISING (FFAB)	FREISING (FFAB)	FREISING (FFAB)
Wafer Process	LBC7	-	-

- QBS: Qual By Similarity

- Qual Device TPS22913CYZVR is qualified at LEVEL1-260C

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	QBS Product Reference: TPD12S015YFF	QBS Package Reference: SN74LVC1G04YZVR	QBS Package Reference: TXS0104EYZTR
AC	Autoclave 121C	96 Hours	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-
EDR	EEPROM Data Retention, 150C	Post 1000 Hours	1/77/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
HBM	ESD - HBM	2500 V	1/3/0	-	-
HBM	ESD - HBM-HIGH	15000 V	1/3/0	-	-
CDM	ESD - CDM	1000 V	1/3/0	-	-
HTOL	Life Test, 150C	300 Hours	1/77/0	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	3/231/0
LU	Latch-up	(per JESD78)	1/6/0	-	-
PD	Physical Dimensions	--	-	Pass	Pass
SBS	Bump-shear	Bumps	-	1/50/0	3/150/0
TC	Temperature Cycle, -55/125C	1000 Cycles	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>